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L Number	Hits	Search Text	DB	Time stamp
1	43	epoxy near4 anhydride near4 silica	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 15:29
2	6	(epoxy near4 anhydride near4 silica) and light	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 15:32
3	2	(light near4 sensitive) and encapsulant and resin and (flip adj chip) and @ad<19990510	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 15:34
-	2799	((438/614) or (257/772) or (228/180.22)).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/17 14:52
-	2509	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 13:30
-	1222	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510 and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 13:31
-	938	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510 and solder) and (bump or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 13:39
-	34	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510 and solder) and (bump or ball)) and (resin near4 coat\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 14:10
-	548	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510 and solder) and (bump or ball)) and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 14:13
-	3	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510 and solder) and (bump or ball)) and second) and (photo\$ near4 resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 14:20
-	0	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510 and solder) and (bump or ball)) and second) and (epoxy adj anhydride)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 14:22
-	165	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510 and solder) and (bump or ball)) and second) and resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 14:23
-	107	((438/614) or (257/772) or (228/180.22)).CCLS.) AND @ad<19990510 and solder) and (bump or ball)) and second) and resin) and epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 14:54

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-	12573	flip adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 14:55
-	9536	(flip adj chip) and @ad<19990510	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 14:58
-	3612	((flip adj chip) and @ad<19990510) and (solder near4 (ball or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 15:01
-	2379	((flip adj chip) and @ad<19990510) and (solder near4 (ball or bump))) and second	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 15:10
-	20	((flip adj chip) and @ad<19990510) and (solder near4 (ball or bump))) and second) and (photosensitive adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/15 15:06
-	688	((flip adj chip) and @ad<19990510) and (solder near4 (ball or bump))) and second) and resin and epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 12:53
-	688	((flip adj chip) and @ad<19990510) and (solder near4 (ball or bump))) and second) and resin and epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/05/16 12:55